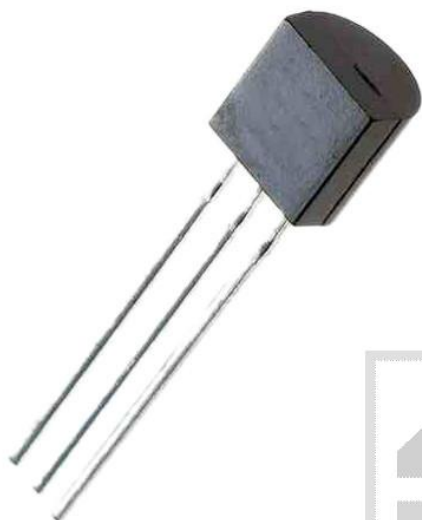




TR BF370;AM;TO92;tranzystor; NPN;100mA;15V;0.5W;500MHz



Dane techniczne:

Nazwa: BF370

Typ tranzystora: bipolarny

Kierunek przewodnictwa: NPN

Prąd kolektora: 100mA

Napięcie kolektor-emiter: 15V

Moc: 500mW

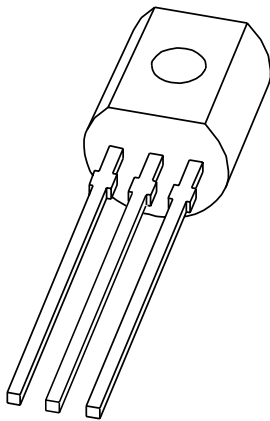
Częstotliwość: 500MHz

Montaż: przewlekany(THT)

Obudowa: TO92

Producent: AM

DATA SHEET



BF370

NPN medium frequency transistor

Product specification
Supersedes data of 1999 Apr 21

2004 Nov 08

NPN medium frequency transistor

BF370

FEATURES

- Low current (max. 100 mA)
- Low voltage (max. 15 V).

APPLICATIONS

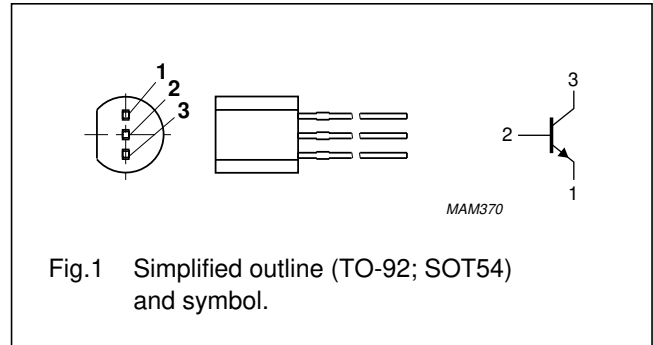
- IF preamplifiers of television receivers.

DESCRIPTION

NPN medium frequency transistor in a TO-92; SOT54 plastic package.

PINNING

PIN	DESCRIPTION
1	emitter
2	base
3	collector



ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BF370	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54

NPN medium frequency transistor

BF370

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	40	V
V_{CEO}	collector-emitter voltage	open base	–	15	V
V_{EBO}	emitter-base voltage	open collector	–	4.5	V
I_C	collector current (DC)		–	100	mA
I_{CM}	peak collector current		–	200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$; note 1	–	500	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	ambient temperature		–65	+150	°C

Note

1. Transistor mounted on an FR4 printed-circuit board.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	250	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS $T_{amb} = 25\text{ °C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector-base cut-off current	$V_{CB} = 20\text{ V}$; $I_E = 0\text{ A}$	–	–	400	nA
		$V_{CB} = 20\text{ V}$; $I_E = 0\text{ A}$; $T_j = 125\text{ °C}$	–	–	30	μA
I_{EBO}	emitter-base cut-off current	$V_{EB} = 2\text{ V}$; $I_C = 0\text{ A}$	–	–	100	nA
h_{FE}	DC current gain	$V_{CE} = 1\text{ V}$; $I_C = 10\text{ mA}$	40	–	–	
C_c	collector capacitance	$V_{CB} = 10\text{ V}$; $I_E = i_e = 0\text{ A}$; $f = 1\text{ MHz}$	–	2.2	–	pF
C_e	emitter capacitance	$V_{EB} = 1\text{ V}$; $I_C = i_c = 0\text{ A}$; $f = 1\text{ MHz}$	–	–	4.5	pF
C_{re}	feedback capacitance	$V_{CB} = 10\text{ V}$; $I_C = 0\text{ A}$; $f = 1\text{ MHz}$	–	1.6	–	pF
f_T	transition frequency	$V_{CE} = 10\text{ V}$; $f = 100\text{ MHz}$				
		$I_C = 10\text{ mA}$	500	–	–	MHz
		$I_C = 40\text{ mA}$	490	–	–	MHz

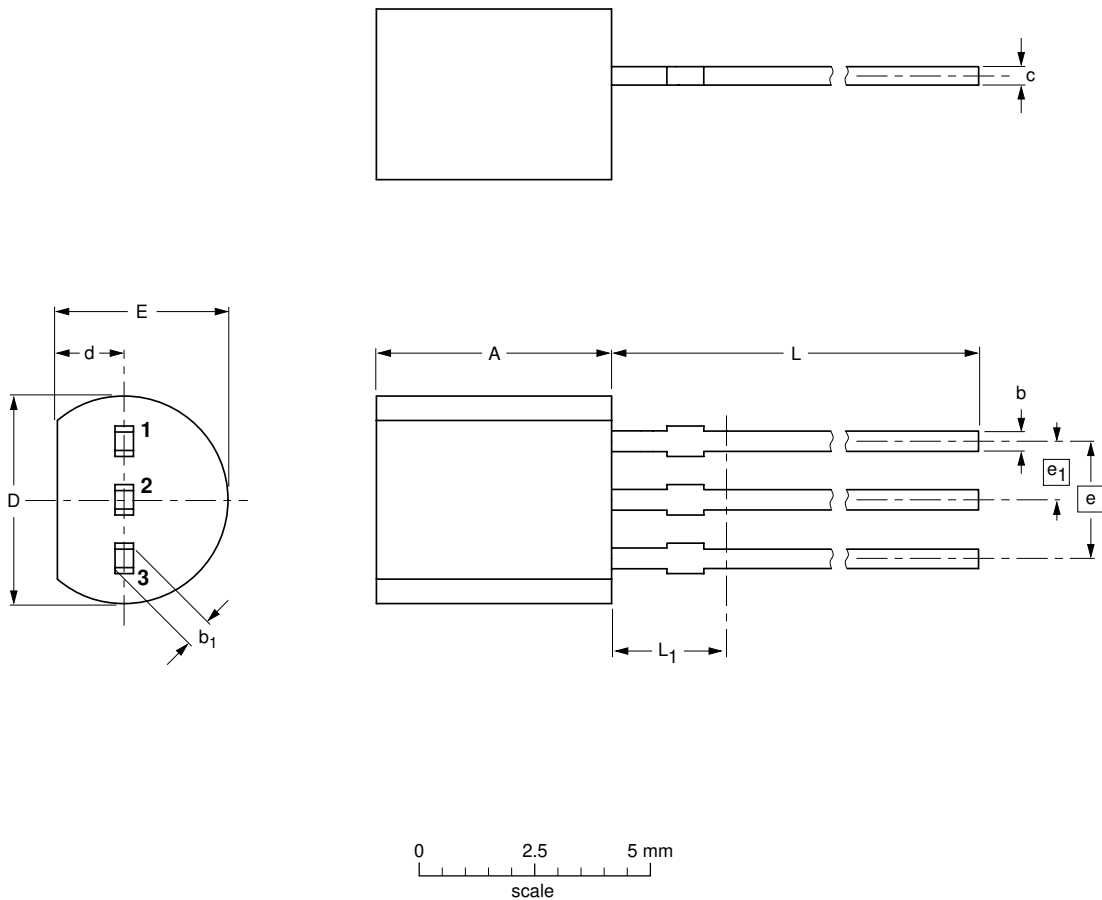
NPN medium frequency transistor

BF370

PACKAGE OUTLINE

Plastic single-ended leaded (through hole) package; 3 leads

SOT54



DIMENSIONS (mm are the original dimensions)

UNIT	A	b	b ₁	c	D	d	E	e	e ₁	L	L ₁ ⁽¹⁾ max.
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

Note

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT54		TO-92	SC-43A		-97-02-28 04-06-28

NPN medium frequency transistor

BF370

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

Notes

1. Please consult the most recently issued data sheet before initiating or completing a design.
2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.
3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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